TOSHIBA LED Lamps

# TLRE1002A(T02), TLSE1002A(T02) TLOE1002A(T02),TLYE1002A(T02),TLPYE1002A(T02) TLGE1002A(T02),TLFGE1002A(T02),TLPGE1002A(T02)

**Panel Circuit Indicators** 

- Surface-mount devices
- $2.0 \text{ (L)} \times 1.25 \text{ (W)} \times 1.1 \text{ (H) mm}$
- InGaAℓP LEDs
- Replacing standard-intensity LEDs with high-intensity ones helps increase the brightness or reduce the power consumption of end products.
- Colors: red, orange, yellow, pure yellow, green, pure green
- Applications:
  - Backlighting for battery-powered equipment
  - Pilot lamps for mobile handsets
  - $Low\mbox{-}power\mbox{ electronic equipment, etc.}$
- Standard embossed tape packing: T02 (3000 pcs / reel)

8-mm tape reel

# **Color and Material**

		$( \bigcirc ) \lor$
Part Number	Color	Material
TLRE1002A	Red	$( \bigcirc \bigcirc )$
TLSE1002A	Red	
TLOE1002A	Orange	$\left( \right) $
TLYE1002A	Yellow	InGaAtP
TLPYE1002A	Pure Yellow	
TLGE1002A	Green	
TLFGE1002A	Green	
TLPGE1002A	Pure Green	
$\sim$	$\sim$	()

Weight: 0.002 g (typ.)

1. Cathod 2. Anode

JEDEC

JEITA

TOSHIBA

Cathode inde

Unit: mm

\_\_\_2

(1.28)

LED chip (0.25)

25

0.4 ± 0.3

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4-1D1

Tolerance: ±0.1

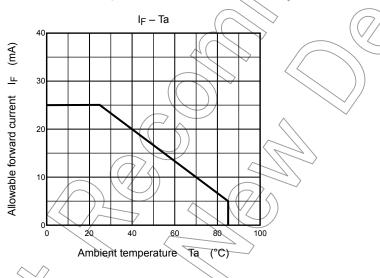
### Absolute Maximum Ratings (Ta = 25°C)

Part Number	Forward Current I <sub>F</sub> (mA) Please see Note 1	Reverse Voltage V <sub>R</sub> (V)	Power Dissipation P <sub>D</sub> (mW)	Operation Temperature T <sub>opr</sub> (°C)	Storage Temperature T <sub>stg</sub> (°C)
TLRE1002A					
TLSE1002A				$\sim$	
TLOE1002A					
TLYE1002A	25	4	60	-40 to 85	-40 to 100
TLPYE1002A	23	-	00	-40 10 85	• -40 10 100
TLGE1002A			$\sim$	(7/5)	
TLFGE1002A					
TLPGE1002A				$\bigcirc$	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### Note 1: Forward current derating



# Electrical Characteristics (Ta = 25°C)

Part Number	Forward Voltage V <sub>F</sub>			Reverse Current I <sub>R</sub>		
	Min	Typ?	Min	/ IF	Max	VR
TLRE1002A	1.6	1.9	2.4			
TLSE1002A	1.6	1.9	2.4	20	50	4
TLOE1002A	1.6	2.0	2.4			
TLYE1002A	1.6	2.0	2.4			
TLPYE1002A	1.6	2.0	2.4			
TLGE1002A	1.6	2.0	2.4			
TLFGE1002A	1.6	2.0	2.4			
TLPGE1002A	1.6	2.1	2.4			
Unit		V		mA	μΑ	V

# **Optical Characteristics-1 (Ta = 25°C)**

Part Number	Luminous Intensity I <sub>V</sub>			Available Iv rank		
T art Number	Min	Тур.	Max	١ <sub>F</sub>	Please see Note 2	
TLRE1002A	27.2	70	_	20	L/M/N/P	
TLSE1002A	47.6	140	_	20	M/N/P/Q	<
TLOE1002A	47.6	180	_	20	M/N/P/Q	
TLYE1002A	27.2	105	_	20	L/M/N/P	
TLPYE1002A	27.2	70	_	20	L/M/N/P	
TLGE1002A	27.2	70	_	20	L/M/N/P	$\langle \rangle$
TLFGE1002A	8.5	25	_	20	J/K/L/M	$\leq$
TLPGE1002A	4.76	18	_	20	H/J/K/L (	1
Unit	mcd	mcd	mcd	mA		)

Note 2: The specification on the above table is used for Iv classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

Luminous Intensity IV				
Min	Max			
4.76	12.9			
8.5	23			
15.3	41.4			
27.2	73.6			
47.6	129			
85	230			
153	414			
272	736			
mcd	mcd			
	Min 4.76 8.5 15.3 27.2 47.6 85 153 272			

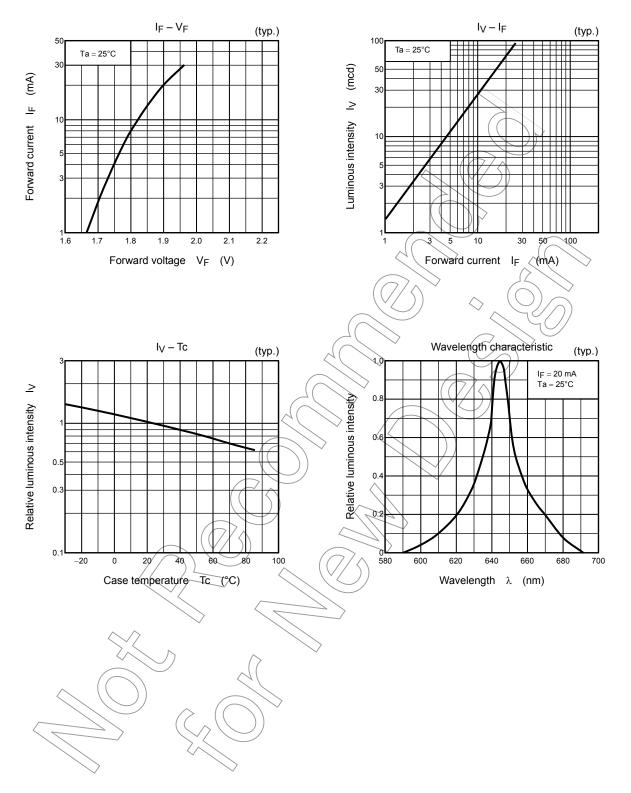
# Optical Characteristics-2 (Ta = 25°C)

	Emission Spectrum							
Part Number	Peak Emission $\langle \lambda_p \rangle$		$\Delta \lambda$ Dominant Wavelength $\lambda_d$			١F		
$\frown$	∕>Min	Тур.	Max	Тур.	Min	Тур.	Max	•
TLRE1002A	$\langle \cdot \rangle$	644		18	624	630	638	
TLSE1002A		623	$\overline{\langle}$	17	607	613	621	
TLOE1002A	$) \rightarrow$	612		15	599	605	613	
TLYE1002A	2_	590		13	581	587	595	20
TLPYE1002A		583		13	574	580	586	20
TLGE1002A		574	/	11	565	571	576	
TLFGE1002A	_	568	<u> </u>	11	559	565	571	
TLPGE1002A	_	562	_	11	_	558	564	
Unit		nm		nm		nm		mA

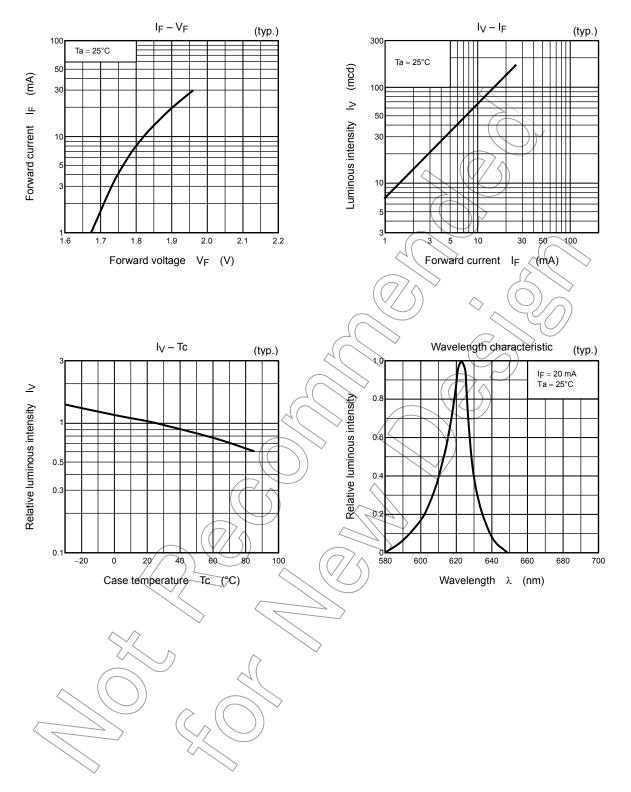
#### Cautions

- This visible LED lamp also emits some IR light.
- If a photodetector is located near the LED lamp, please ensure that it will not be affected by the IR light.
  This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

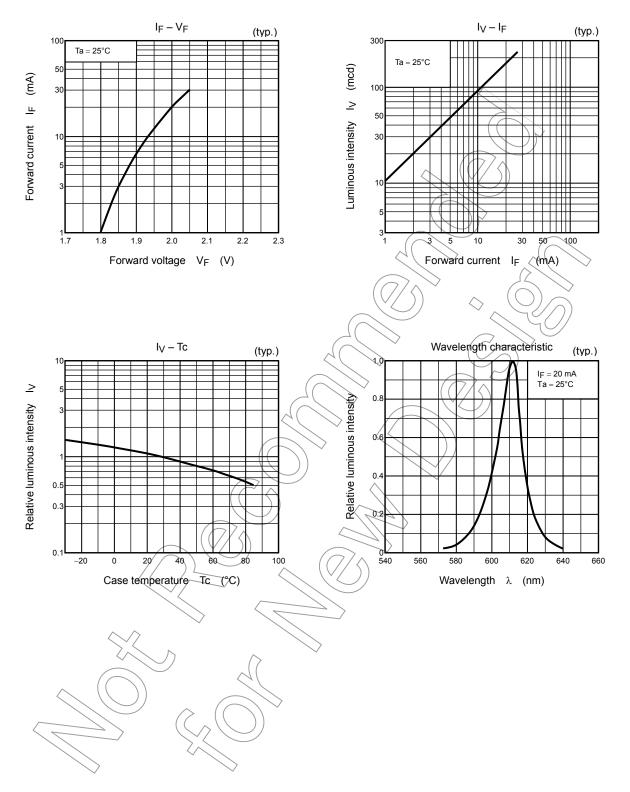
### TLRE1002A



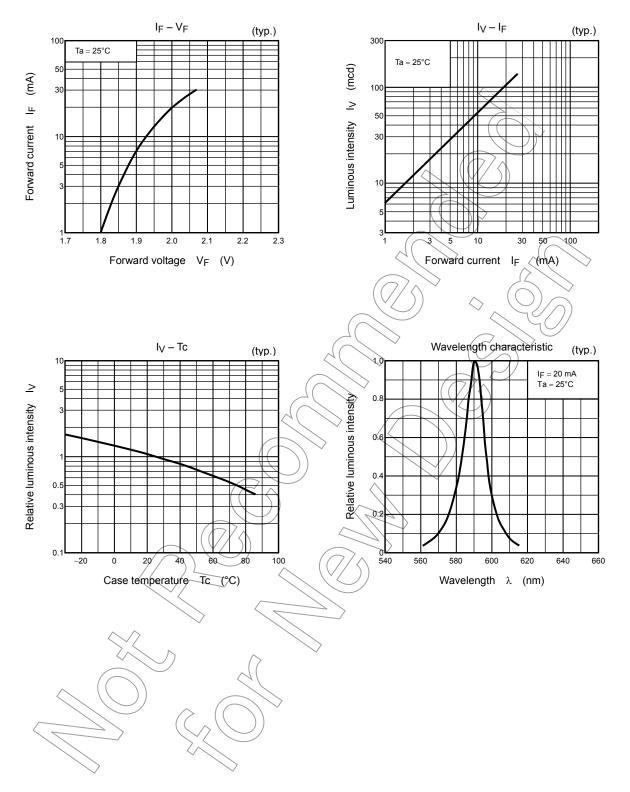
### TLSE1002A



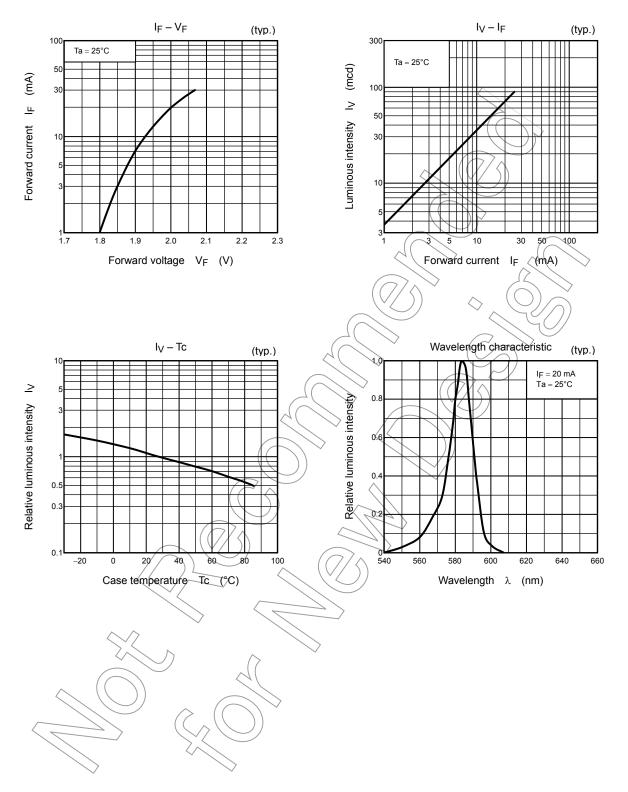
## TLOE1002A



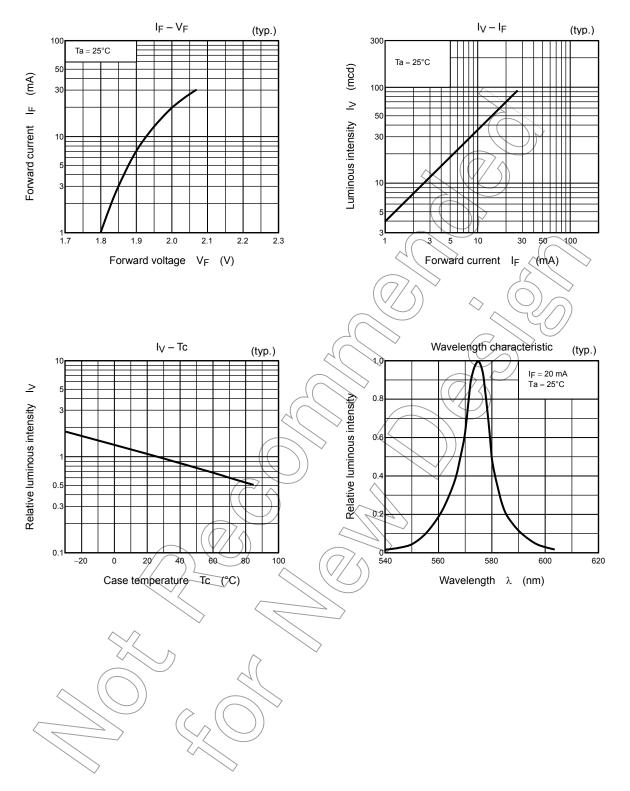
### TLYE1002A



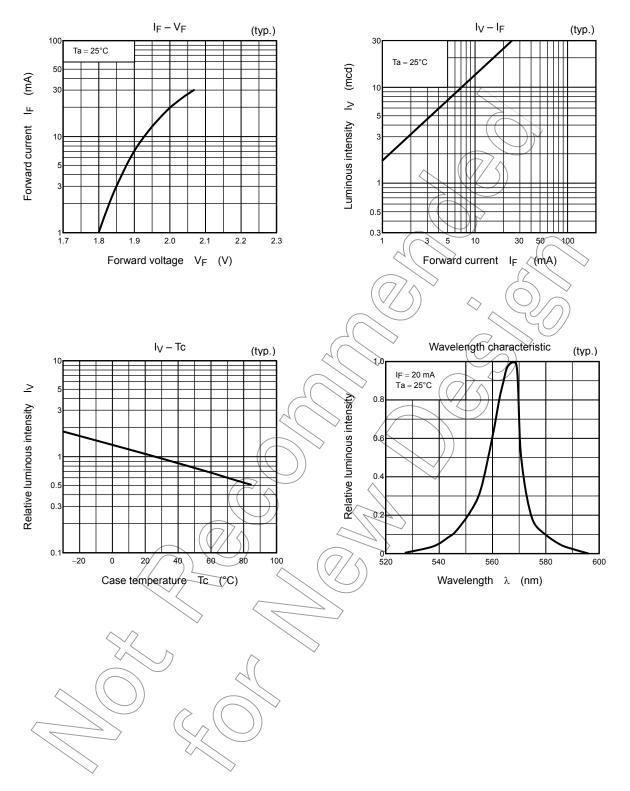
## TLPYE1002A



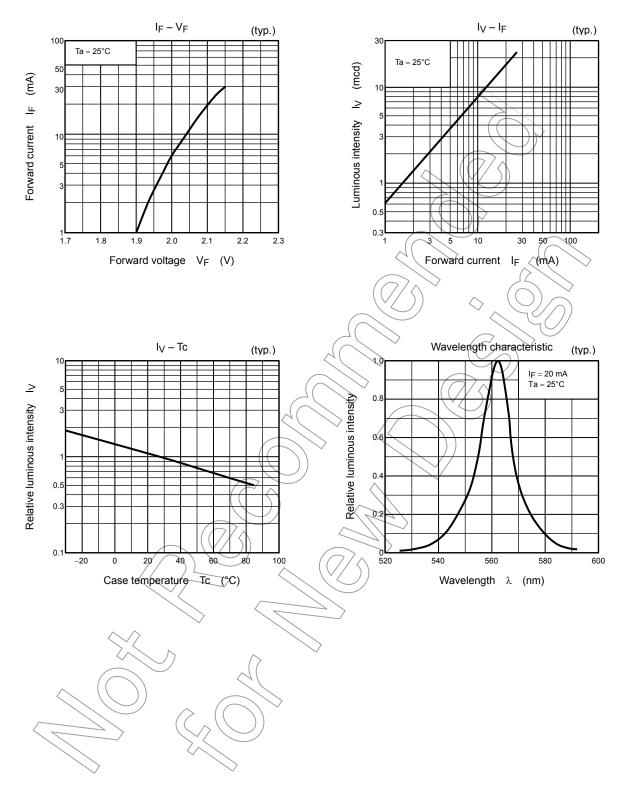
### TLGE1002A



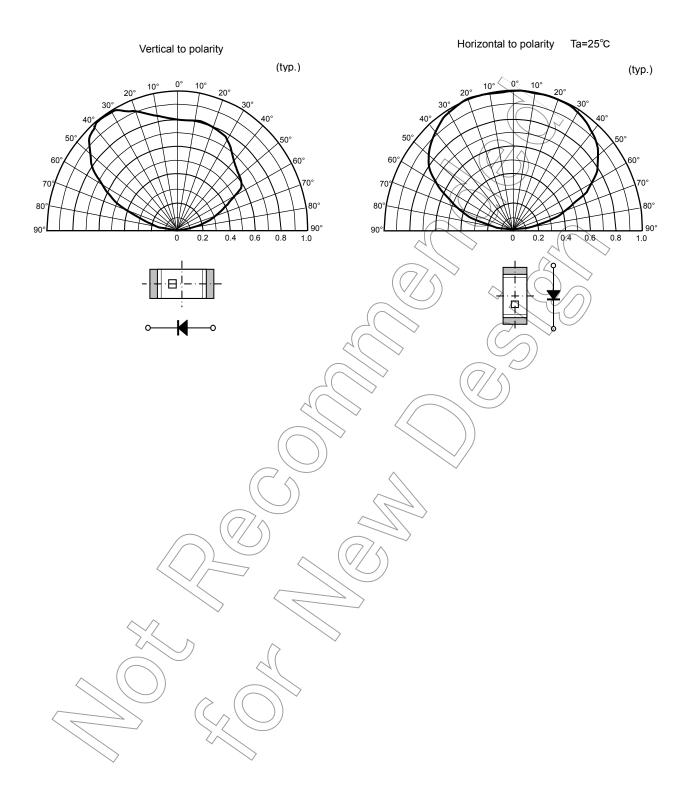
## TLFGE1002A



## TLPGE1002A



# **Radiation Pattern**



# Packaging

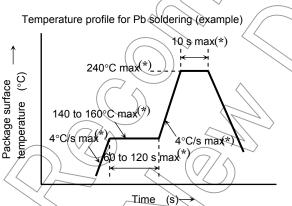
These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

- This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5°C to 30°C Humidity: 90% (max)
- After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/70% RH or below.
   When performing lead(Pb)-free soldering, the devices should be assembled within 72 hours in an environment of 5°C to 30°C/70% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel. After baking, use the baked devices within 72 hours, but perform baking only once. Baking conditions: 60±5°C, for 12 to 24 hours. Expiration date: 12 months from sealing date, which is imprinted on the same side as this label affixed.
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- 5. If the packing material of laminate would be broken, the air tightness would deteriorate. Therefore, do not throw or drop the packed devices.

### **Mounting Method**

#### Soldering

• Reflow soldering (example)



- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (\*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering In case of second reflow soldering should be performed within 168 h of the first reflow under the above

conditions.

Storage conditions before the second reflow soldering: 30°C, 70% RH (max)

Make any necessary soldering corrections manually.

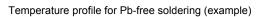
(only once at each soldering point)

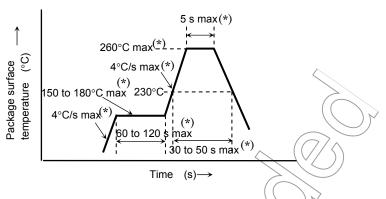
Soldering iron: 25 W Temperature : 300°C or less

Time : within 3 s

• Do not perform wave soldering.

• Reflow soldering (example)





- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (\*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 72 h of opening the package.

1.2

(12)

- Second reflow soldering In case of second reflow soldering should be performed within 72 h of the first reflow under the above conditions.
- Storage conditions before the second reflow soldering: 30°C, 70% RH (max)
  Make any necessary soldering corrections manually.

1.2

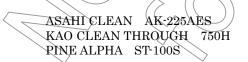
1.0

- (only once at each soldering point)
  - Soldering iron: 25 W
  - Soldering fron: 25 W
  - Temperature : 300°C or less
- Time : within 3 s Do not perform wave soldering.

# Recommended soldering pattern

#### Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.



: (made by ASAHI GLASS)

Unit: mm

- : (made by KAO)
- : (made by ARAKAWA CHEMICAL)

# Precaution when mounting

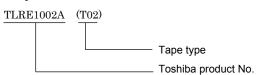
Do not apply force to the plastic part of the LED under high-temperature conditions. To avoid damaging the LED plastic, do not apply friction using a hard material. When installing the PCB in a product, ensure that the device does not come into contact with other cmponents.

#### Tape Specifications

#### 1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (However, this method does not apply to products whose electrical/optical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T02 (4-mm pitch)
- (2) Example

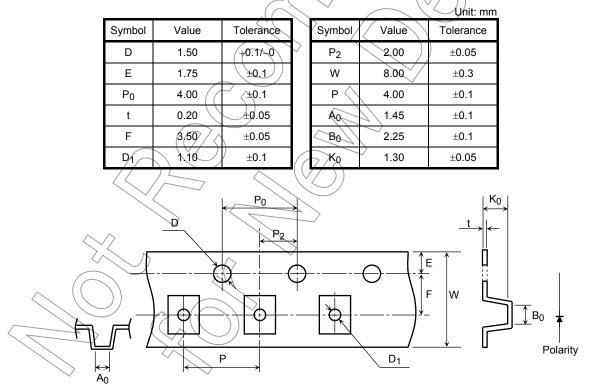


#### 2. Handling precautions

Tape material protected against static electricity. However, static electricity may occur depending on quantity of charged static electricity and a device may attach to a tape, or a device may be unstable when peeling a tape cover.

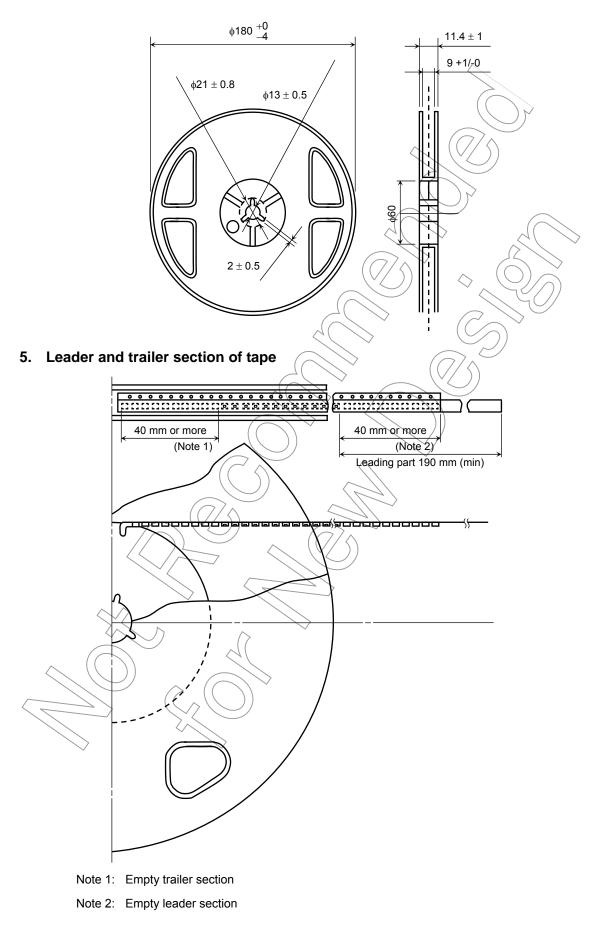
- (a) Since tape materials may accumulate an electrostatic charge, use an ionizer to neutralize the ambient air.
- (b) For transport and temporary storage of devices, use containers (boxes and bags) and jigs that are made of anti-static materials or of materials which dissipate electrostatic charge.

#### 3. Tape dimensions



#### 4. Reel dimensions

Unit: mm



#### 6. Packing display

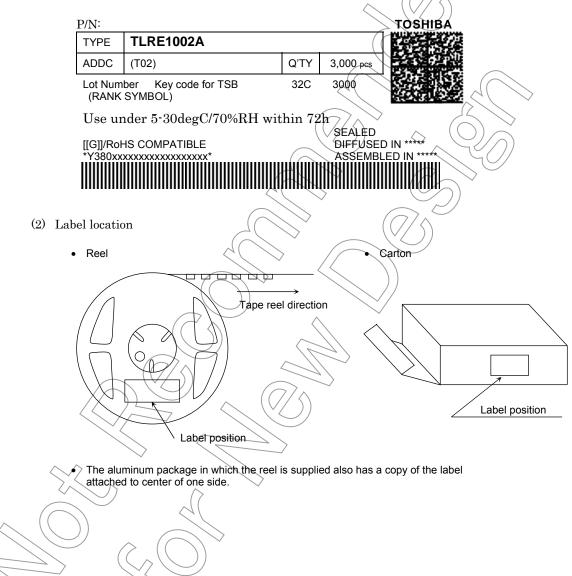
(1) Packing quantity

Reel	3,000 pcs
Carton	15,000 pcs

(2) Package form: Each reel is sealed in an aluminum pack with silica gel.

#### 7. Label format

(1) Example: TLRE1002A (T02)



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